

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	(semiconductor or die or chip or IC) same (heat near (sink or spread\$3 or transfer or radiat\$3) or cap or lid) and thermal near grease same silicon near rubber with particle	USPAT	OR	ON	2005/03/16 23:06
L2	0	(semiconductor or die or chip or IC) same (heat near (sink or spread\$3 or transfer or radiat\$3) or cap or lid) and thermal near grease and silicon near rubber with particle	USPAT	OR	ON	2005/03/16 23:07
L3	3	(semiconductor or die or chip or IC) same (heat near (sink or spread\$3 or transfer or radiat\$3) or cap or lid) and thermal near grease same silicon with particle	USPAT	OR	ON	2005/03/16 23:09
L4	1	(semiconductor or die or chip or IC) same (heat near (sink or spread\$3 or transfer or radiat\$3) or cap or lid) and thermal near grease same (silicon or silicone or "Si") with rubber with (particle or filler)	USPAT	OR	ON	2005/03/16 23:32
L5	0	(semiconductor or die or chip or IC) same (heat near (sink or spread\$3 or transfer or radiat\$3) or cap or lid) and thermal near grease same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:34
L6	0	thermal near grease same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:34
L7	0	thermal near (grease or compound) same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:34
L8	0	thermal near (grease or compound material) same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:35
L9	0	thermal near (grease or compound or material or resin) same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:36

L10	0	thermal near (grease or compound or material or resin or adhesive or glue) same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:47
L11	3	thermal near (grease or compound or material or resin or adhesive or glue) and (grease or compound or material or resin or adhesive or glue) same epoxy near resin with curing near agent with catalyst with coupling with agent	USPAT	OR	ON	2005/03/16 23:54
L12	0	thermal near (grease or compound or material or resin or adhesive or glue) and (grease or compound or material or resin or adhesive or glue) same epoxy near resin with curing near agent with catalyst with coupling with agent with (fillers or particles) with flame near retardant	USPAT; JPO	OR	ON	2005/03/17 00:35
L13	3646	257/723	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 00:28
L14	123	508/161	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 00:28
L15	1	thermal with (grease or compound or material or resin or adhesive or glue) and (grease or compound or material or resin or adhesive or glue) same epoxy near resin with curing near agent with catalyst with coupling with agent with (fillers or particles) with flame near retardant	USPAT; JPO	OR	ON	2005/03/17 00:36
L16	0	thermal with (grease or compound or material or resin or adhesive or glue) and (grease or compound or material or resin or adhesive or glue) same epoxy near resin with curing near agent with catalyst with coupling with agent with (fillers or particles) with flame near retardant with (mold\$3 or encapsulat\$3) near releas\$3 near agent	USPAT; JPO	OR	ON	2005/03/17 00:36